Component Title:

DIODES, MICROWAVE, SILICON, SCHOTTKY, GENERAL PURPOSE, BASED ON TYPES BAS40, BAS70, BXY42, BXY43, BXY44

Page 1 Appl. No.

Executive Member:

DLR

Date: 10/11/2019

227H

Components (include	ling series and families) s	submitted for Extensi	on of Qualification	Approval:				1
ESCC COMPONENT VARIANTS NO.		RANGE OF C	OMPONENTS	BASEI ON		EST ICLE / S	COMPONENT SIMILAR	
5512/020	01, 03			BAS40 & 70		BAS70-T1(ES)		
5513/017	01, 02			BXY42	BAS70-T			
5513/030	01, 02, 05, 06	j		BXY43 & 44	4			
Component I		Location of I Am Campeon 1-1 D- 85579 Neubibe Germany		nt(s)		nal qualification 01/09/1996 ef 227	approval:	4
ESCC Specification Maintenance of qua Generic: 5010		Deviations to LVT used:	testing and Detail		reference an	Extension Repo d date: ss. 1, Sep 2019		7
Detail(s): 5512/0		1000 E	rrent Specification					
Summary of procur	rement or equivalent test	results during curren	t validity period in	support of this a	application (those to	ESCC listed fir	rst)	8
Project Name	Testing Level	LAT		Date code			Delivered	
PID changes since	last MoQ		9 Current PID by:	Verified	Bura	k Gökgöz		10
None □ Minor* ⊠	*Provide details in box Gen. PID: 650V Powe implemented Det. PID: updated bas during ESCC Executiv 10.10.2019	r MOSFET device is ed on the agreemen	BAS40 & 70	Detail PID: A6	Name of Ex 3500-GEPID-P000, 3500-D336-P000, I 3500-D329-P000, I	ssue 3, 16.10.20	9.2019 019	
Current Manufactu	ring facilities surveyed by	r:	T. Kaupis	sch	on	17-1	8/10/2018	11
		(N	ame of Executive	Representative)	9	(Date)	
Satisfactory:	Yes ⊠	No 🗆	Explain					
Report Reference	IFX-AUD-2018							

Cant .	ES	CC	
	ASS		0

Component title:

DIODES, MICROWAVE, SILICON, SCHOTTKY, GENERAL PURPOSE, BASED ON TYPES BAS40, BAS70, BXY42, BXY43, BXY44

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	Executive Member:	DLR		Date:	10/11/2019	227H
Failure Analysis, DPA, NCCS ava	ilable: Yes	□ No				12
Ref. No's and purposes:						
The undersigned hereby certifies on behalf that the appropriate documentation has bee (except as stated in box 15;) - that the repo DLR as the responsible Executive Member	en evaluated; - that fu rts and data are avail	II compliance to able at the ESO	o all ESCC requirements CC Executive and theret	s is eviden fore applie:	s on behalf of	13
Date: 10/11/2019					Bill Sole Gl Burak Gökgöz	
				(S	ignature of the Executive	
Continuation of Boxes above:						14

Component title:

DIODES, MICROWAVE, SILICON, SCHOTTKY, GENERAL PURPOSE, BASED ON TYPES BAS40, BAS70, BXY42, BXY44, BXY44

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DIR

Date: 10/11/2019

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	Excounter	nombon. Dail		
Non comp	pliance to ESCC requirements:		_1	15
No.:	Specification	Paragraph	Non compliance	
	Gp com			
				16
Executive	e Manager Disposition			17
LACCULIV	/			17
Application	on Approval: Yes 🕤 No 🗆			1
Action / F	Remarks:			
Date:	24.1.20Ro		301	
	4.7		B. Schade, Head of ESA Product Assuranc and Safety Department	е



Component Title:

DIODES, MICROWAVE, SILICON, SCHOTTKY, GENERAL PURPOSE, BASED ON TYPES BAS40, BAS70, BXY42, BXY43,

Page 4 Appl. No.

BXY44

Executive Member: DLR Date: 10/11/2019 227H

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ANNEX 1: LIST O	OF TESTS DONE TO SUPPORT	EXTENSION OF QUALIFICATION
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Tests conducted in compliance with:

ESCC 5010 generic specification; Chart F4 (for ESCC/QPL parts);

Tests vehicle identification/description:

1922LR11	BAS70-T1(ES)	

Chart F4A	Test	Tick when done	Conditions	Date Code Diffusion Lot	Tested Qty	No. of Rejects	Comments if not performed. Comments on Rejection
	Thermal Shock Test	×	ESCC 5010 Para. 9.5.2	1814A	8	0	
S	Shock Test		MIL-STD-750 Test Method 2016		_		n.a. acc. Detail Spec
group	Vibration Test		MIL-STD-750 Test Method 2056				n.a. acc. Detail Spec
al Sub	Constant Acceleration		MIL-STD-750 Test Method 2006				n.a. acc. Detail Spec
chanio	Seal Test		MIL-STD-750 Test Method 1071				n.a. acc. Detail Spec
al/Mec	Moisture Resistance	⊠	MIL-STD-750 Test Method 1021	1814A	8	0	
numen	Seal Test	⊠	MIL-STD-750 Test Method 1071	1814A	8	0	
Environmental/Mechanical Subgroups	Electrical Measurements at Room Temp.	⊠	Table 2 of the Detail Specification	1814A	8	0	4
	External Visual Inspection	⊠	ESCC Basic Specification No. 20500	1814A	8	0	
Endurance Subgroup*	Operating Life		MIL-STD-750 Test Method 1026				Former data from Wafer available
	Electrical Measurements during Endur. Test		Table 6 of the Detail Specification				Former data from Wafer available
	External Visual Inspection		ESCC Basic Specification No. 20500				Former data from Wafer available

 $^{^{\}star}$ LAT2 on actual wafer was performed satisfactorily on DC 9447A

Chart F4B	Test	Tick when done	Conditions	Date Code Diffusion Lot	Tested Qty	No. of Rejects	Comments if not performed. Comments on Rejection
o – ents	Electrical Measurements at Room Temp.		Table 2 of the Detail Specification				
Electrical Subgroup – Electrical Measurements	Electrical Measurements at High & Low Temp's		Table 3 of the Detail Specification				
lectrical ectrical N	External Visual Inspection		ESCC Basic Specification No. 20500				
<u></u>	Special Testing		The Detail Specification				n.a. acc. Detail Spec
Electrical Subgroup - Assembly Capability Tests	Solderability Test	Ø	MIL-STD-750 Test Method 2026	1814A	4	0	
	Permanence of Marking		ESCC Basic Specification No. 24800				n.a. due to laser marking
	Terminal Strength	⊠	MIL-STD-750 Test Method 2036	1814A	4	0	
De- encapsulation Tests	Internal visual inspection	×	ESCC Basic Specification No. 20400	1814A	6	0	
	Bond Strength	×	MIL-STD-750 Test Method 2037	1814A	6	0	
	Die Shear	×	MIL-STD-750 Test Method 2017	1814A	6	0	



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NOTES ON THE COMPLETION OF THE APPLICATION FORM FOR ESCC QUALIFICATION EXTENSION APPROVAL

ENTRIES	
ENTRIES Form heading	shall indicate: - the title of the component as given in its detail specification or the name of the series, family; - the Executive Member; - the entering date; - the certificate number and its sequential suffix.
Box 1	shall provide details given in the table; in particular there shall be listed: - the variants or range of variants; - the range of components (the ESCC code is recommended to indicate the values or values range, the tolerance, the voltage, etc); the designation given in the detail specification as 'base on'; - under Test Vehicle enter either an ESCC code or the specific characteristic capable of identifying the component tested (e.g., voltage of coil for a relay); - under component similar enter a cross if relevant.
Box 2; 3 and 4	As per QPL entry; otherwise, an explanation of the changes must be supplied.
Box 5	Will show the ESCC Generic and Detail specifications, including issue number and revision letter, current at the time the tests reported were performed. If the specifications are different from those current on the date of the application, see Box 6.
Box 6	Will show the deviations from the Generic and Detail Specifications listed in Box 5, in particular deviations from testing. In case of deviations this must be listed in Box 15. In case the referenced specification in Box 5 have currently a different issue and/or revision indicate also whether the test data deviates or not from such current documents.
Box 7	Must reference the report(s) supplied in support of the application.
Box 8	Should provide the details of procurement to the full ESCC System, documentation of all of which should already have been delivered to the ESCC Executive under the terms of the relevant Generic Specification. An appropriate table has been drawn in this box.
Box 9	If the PID evolved after the Original Qualification or after the last Extension of Qualification, adequate details of such evolution shall be provided together with the reasons for the changes. Major changes shall be clearly marked.
Box 10	Identify the current PID issue status, date and actual date of verification. The date of verification of the current PID should be arranged as close as possible to the required date of extension.
Box 11	This box can be completed only after a physical visit to the plant to confirm that no unexplained changes occurred and that the practices, procedures, material, etc. used in manufacturing the components are as described in the PID. This survey shall be carried out in accordance with the requirements of ESCC Basic Specification No. 20200 and its findings shall be recorded.
Box 12	Provide details of, or reference to, any Destructive Physical Analysis (DPA) and Failure Analysis reports as well as any Nonconformance(s) (NCCS) occurred during the qualification validity period, stating if established corrective action have produced satisfactory results.
Box 13	Enter only the name of the Executive Member (i.e., CNES, DLR, ESTEC, etc.) and the signature of the responsible Executive Coordinator.
Box 14	To be used when there is a need to expand any of the boxes from 1 through 12. Identify box affected and reference the Box 14 in the relevant Box. Box 14 can be broken into 14a, 14b, etc. if several boxes have to be expanded.
Box 15	Fill in Table as requested.
Box 16	Any additional action deemed necessary by the Executive Member to bring the submitted data to a standard likely to be accepted by the ESCC Executive should be listed herein or the reason(s) to accept the noncompliance.
Box 17	All Executive Manager recommendations on the application itself, special conditions or restrictions, modifications of the QPL or QML entry, letters to the manufacturer, etc. shall be entered clearly in Box 19, signed by the representative for ESA, and dated.
Box 18	Fill in Table as requested.
Box 19	Confidential Details of PID changes including those of a confidential nature, shall be provided.
Box 20	State noncompliance with reference to specification(s) and paragraph(s). To simplify reference in Box 16 each nonconformance shall be sequentially numbered. If relevant state 'None'.
Box 21	Any additional action deemed necessary by the Executive Member to bring the submitted data to a standard likely to be accepted by the ESCC Executive should be listed herein or the reason(s) to accept the noncompliance.
Box 22	Additional Comments.